IN THE SPECIFICATION:

Please insert the following paragraph at page 6, between lines 19 and 20:

Figure 4C is an enlarged detail view of the substrate clamp of Figure 4B.

Please replace the paragraph beginning at page 6, line 21, with the following paragraphs:

Figure 6A depicts a partial view of another embodiment of a carrier head assembly.

Figure 6B is an enlarged detail view of a contact plate.

Please replace the paragraph beginning at page 12, line 21, with the following amended paragraph:

Referring to Figure 4C, the ~~The~~ second clamp 404 generally includes a notch 418 formed on the contact surface near the tip. The notch 418 has a bottom surface 420 that is generally greater in length than the thickness of the substrate 22. A wall 422 of the notch 418 closest the end of the first clamp 404 is generally chamfered or angled to contact the bevel or rounded edge of the substrate 22.

Please replace the paragraph beginning at page 13, line 30, with the following amended paragraph:

Figure 6A depicts a partial view of another embodiment of a substrate carrier assembly 600. The carrier assembly 600 is substantially similar to the carrier assembly 30 described above except wherein a contact plate 602 is disposed on a support plate 604. Generally, the contact plate 602 is disposed on a first side 606 of the support plate 604. The contact plate 602 is comprised of a conductive material and is utilized to bias the substrate 22 during processing. The contact plate 602 is electrically coupled to a

terminal 610 disposed on a second side 612 of the support plate 604. The terminal 610 facilitates coupling the contact plate 602 to a power source (not shown) by a lead 608 that is used to bias the substrate 22.

Please replace the paragraph beginning at page 14, line 7, with the following amended paragraph:

Referring to Figure 6B, the ~~The~~ contact plate 602 is generally located proximate the edge of the substrate 22. The contact plate 602 couples the charge to the substrate 22 directly or to a conductive seed layer 620 disposed on the substrate surface that wraps around the substrate edge to a portion of the substrate backside.

Please replace the paragraph beginning at page 14, line 11, with the following amended paragraph:

Figure 7 depicts another embodiment of a substrate carrier 700. The substrate carrier 700 generally includes a housing 702 defining a central cavity 704 that is open on a bottom 706 and through at least one port 708 disposed in the housing 702. The port 708 is typically sized to allow the substrate 22 carried by a robot (not shown) to be placed within the cavity 704. A thrust plate 710 is disposed in the housing 702 and may be actuated towards the bottom 706 of the housing 702. A ring 712 circumscribing the open portion of the bottom 706 includes a ledge 714 that supports the substrate 22 as the thrust plate 710 urges the substrate 22 against the ring 712. The ring 712 may provide the electrical contact to bias the substrate 22. Alternatively, the thrust plate 710 may alternatively include a contact plate 716 similar to the contact plate 602 described in reference to Figures 6A and 6B.